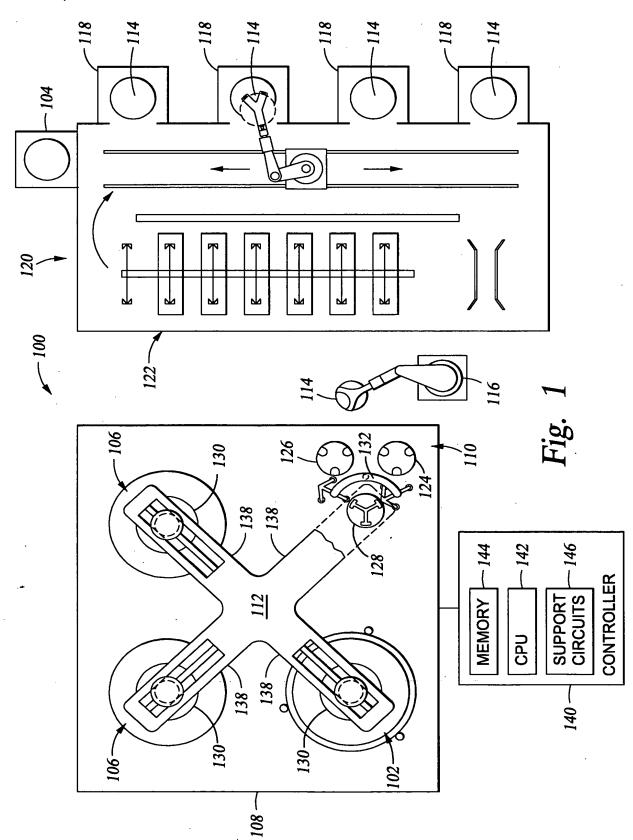
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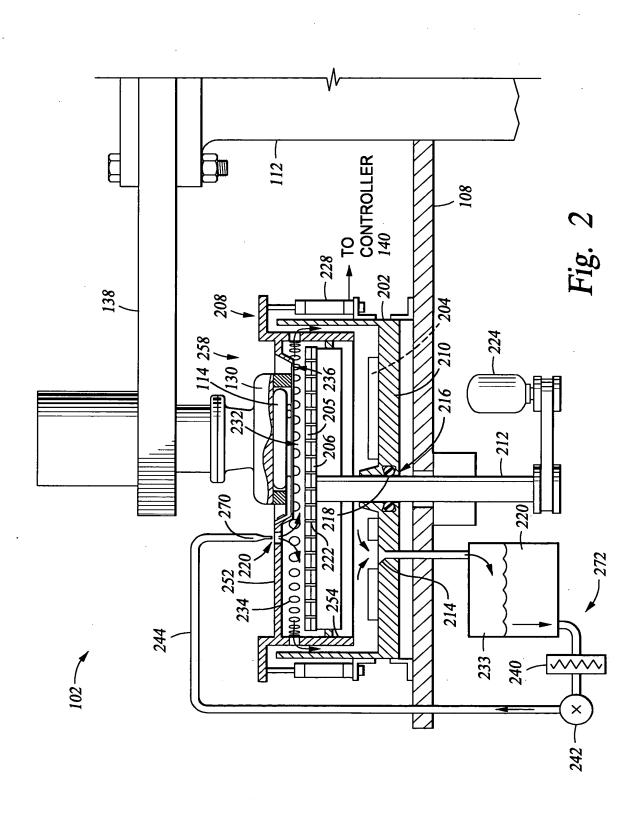
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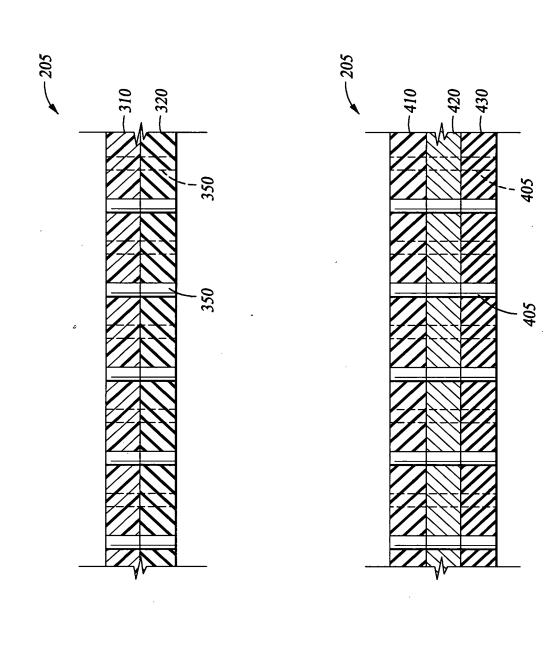


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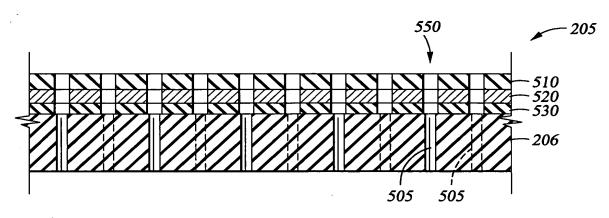


Fig. 5A

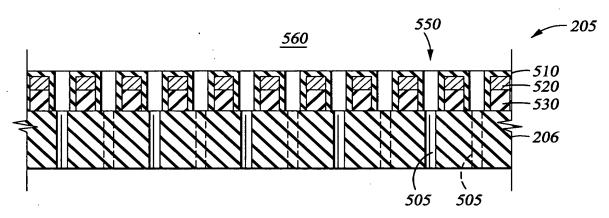


Fig. 5B

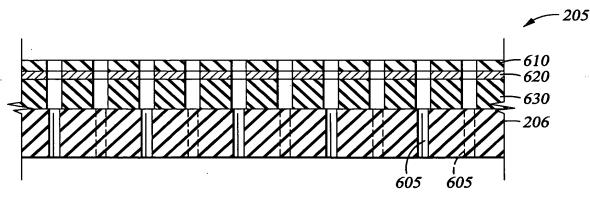


Fig. 6

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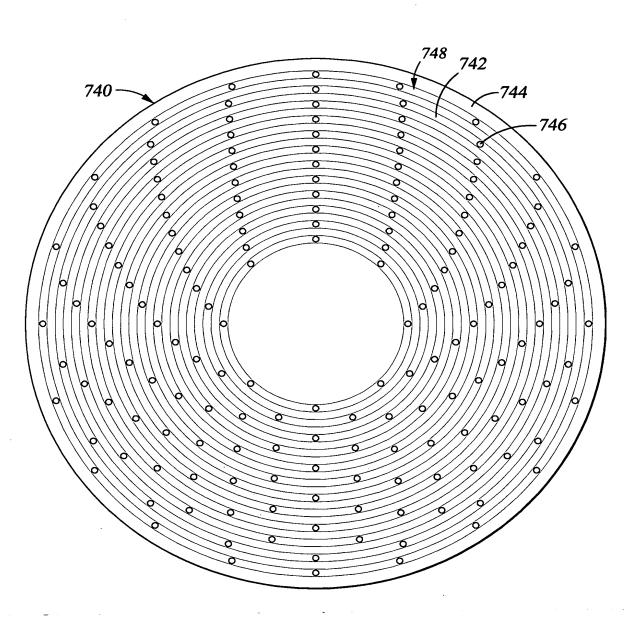


Fig. 7

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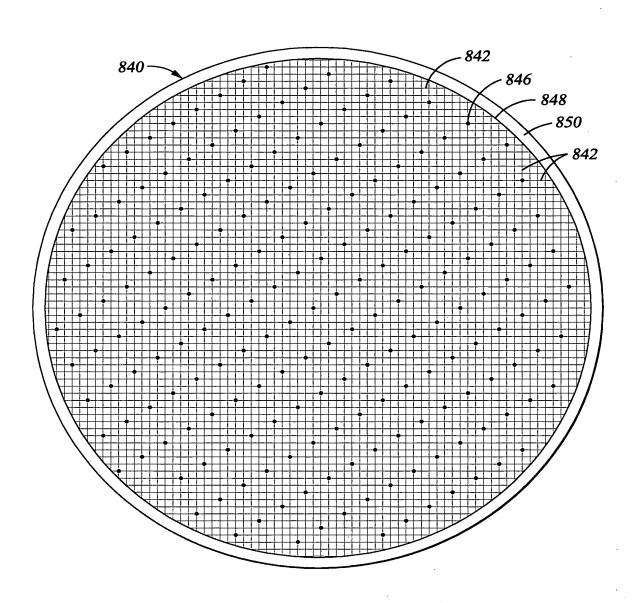


Fig. 8

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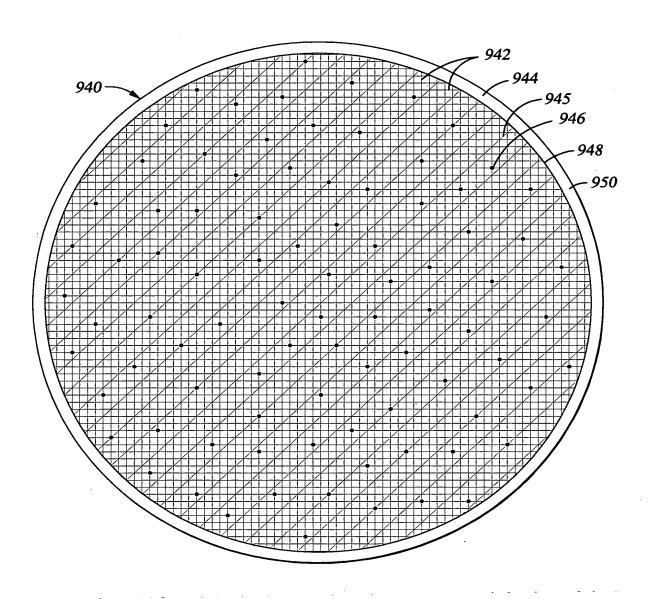
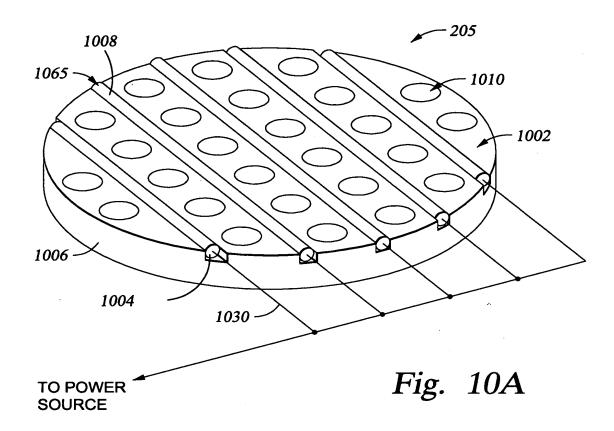
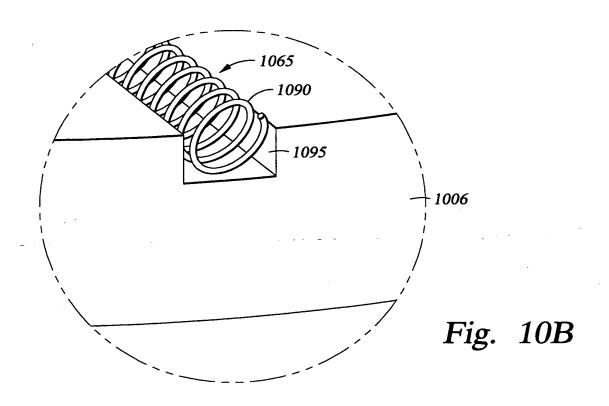


Fig. 9

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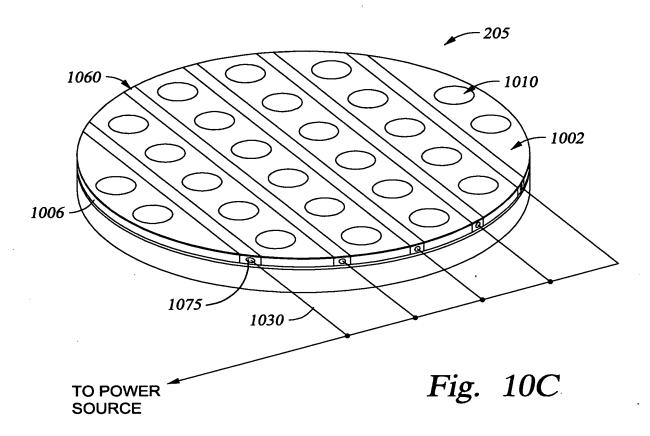
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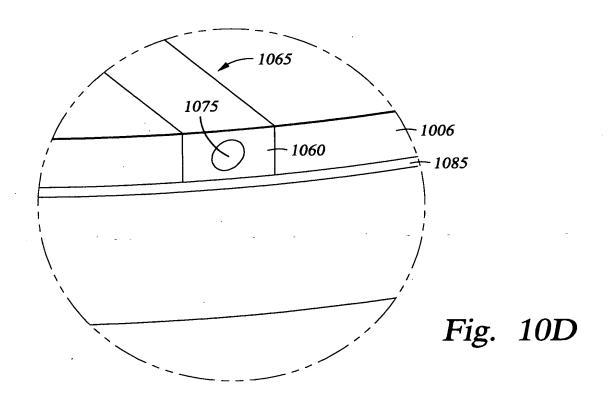
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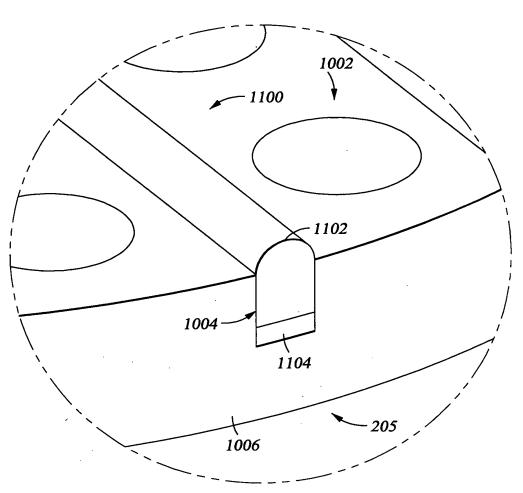
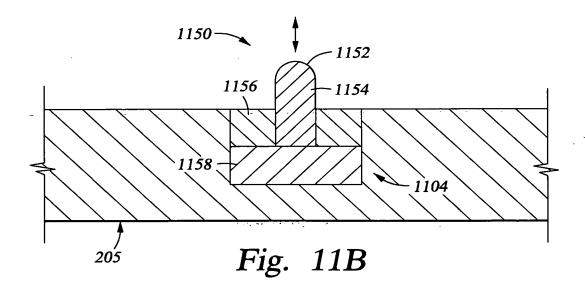


Fig. 11A

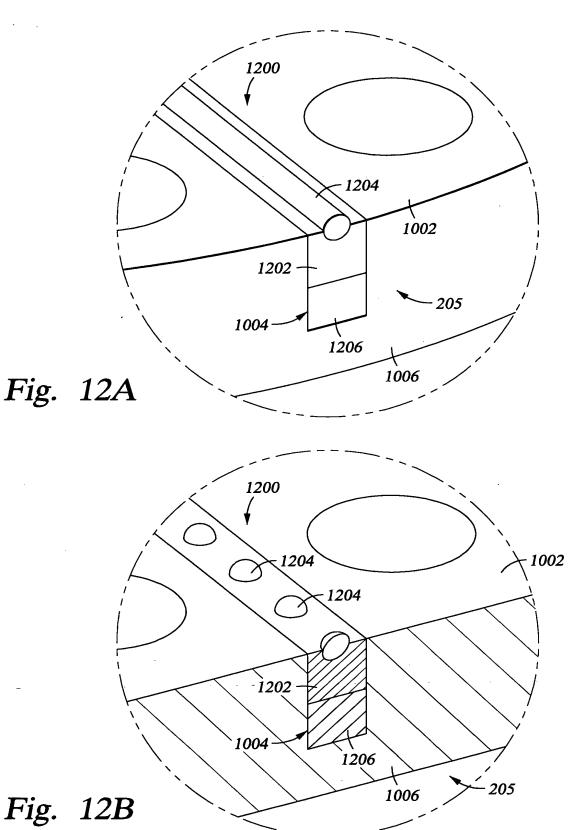


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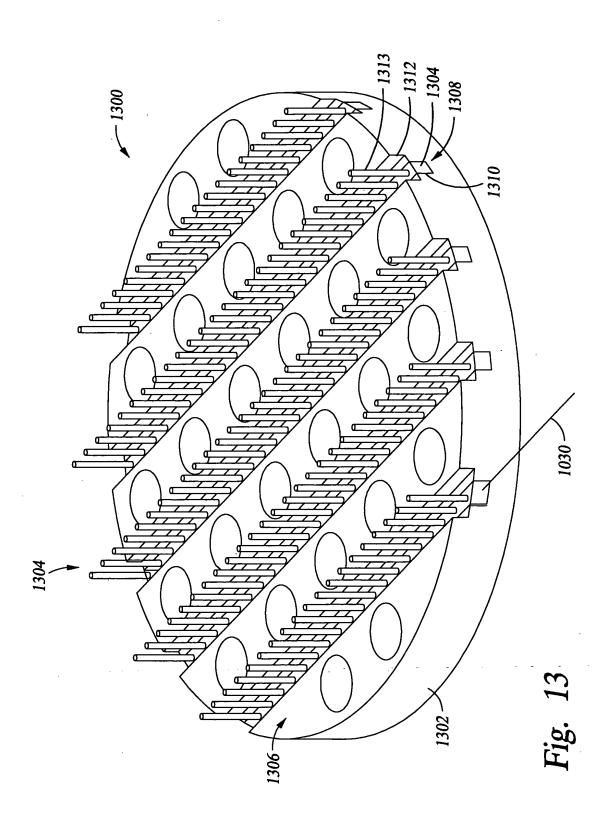
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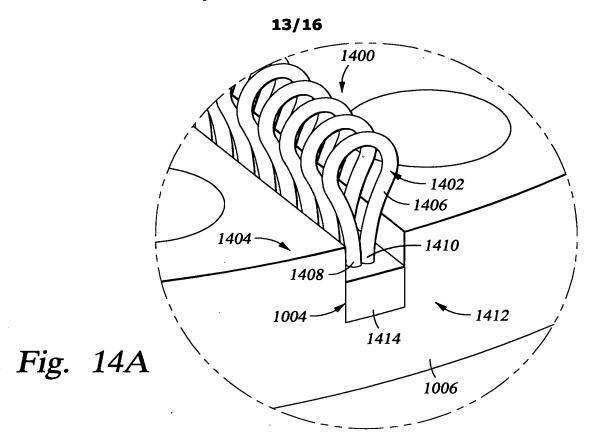
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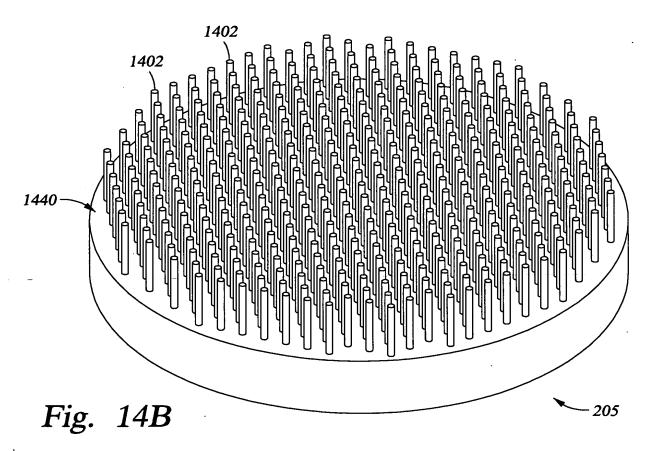
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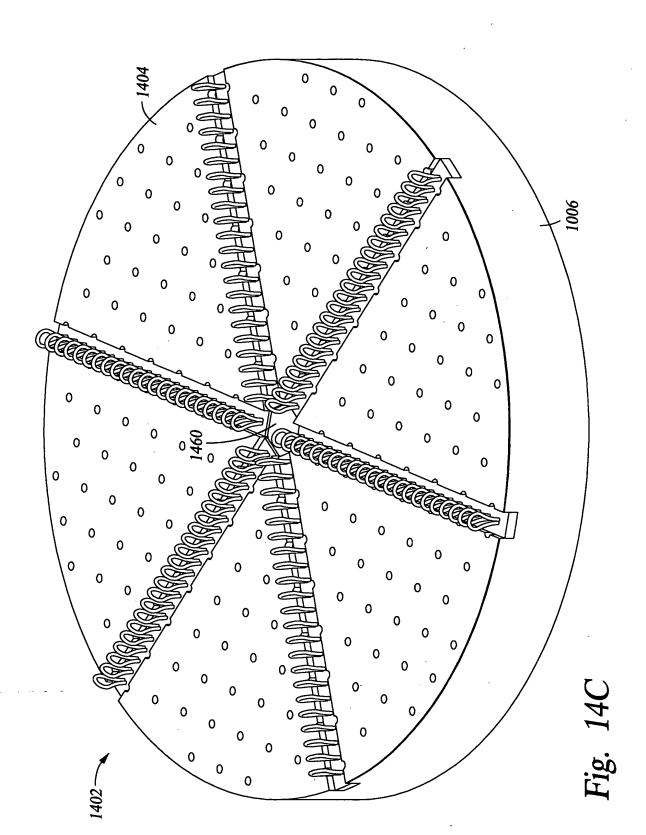




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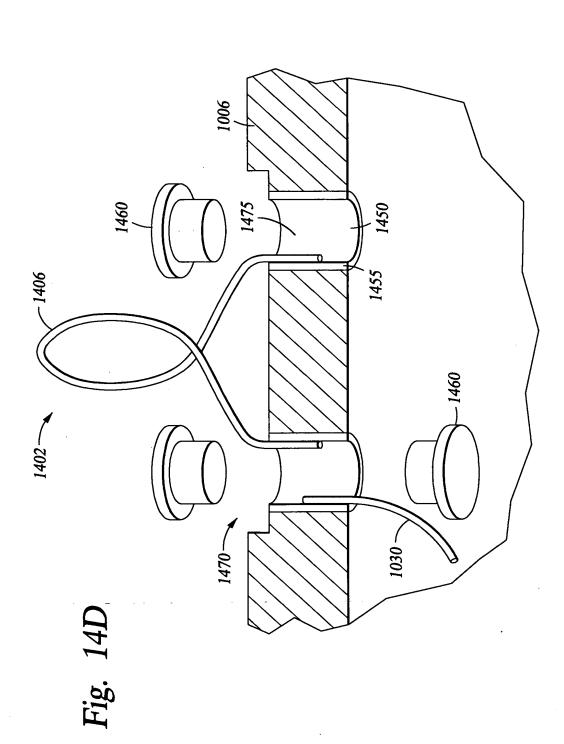
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Fig. 15A

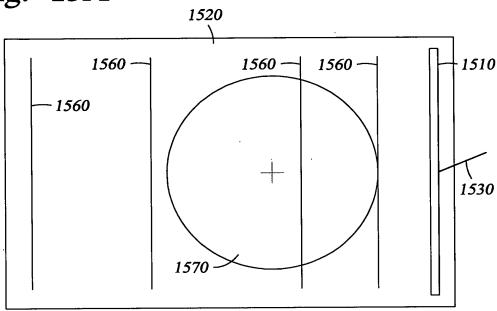


Fig. 15B

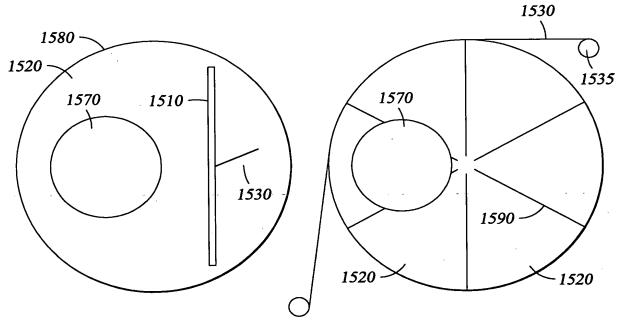


Fig. 15C

Fig. 15D

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